

- ★ Super Low Gate Charge
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology



Product Summary

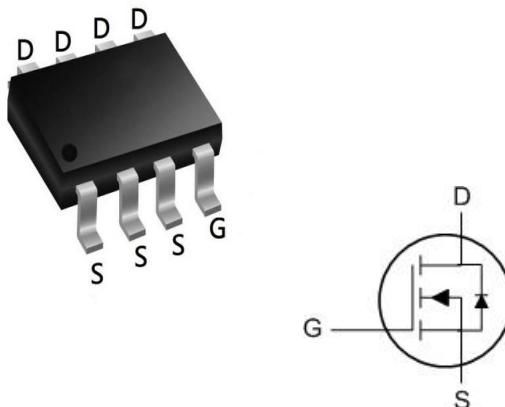
BVDSS	RDS(on)	ID
30V	7.0mΩ	18 A

Description

The XXW4410 is the high cell density trenched N-ch MOSFETs, which provide excellent RDS(on) and gate charge for most of the synchronous buck converter applications.

The XXW4410 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

SOP8 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	30	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	18	A
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	10	A
I _{DM}	Pulsed Drain Current ²	60	A
EAS	Single Pulse Avalanche Energy ³	40	mJ
I _{AS}	Avalanche Current	35	A
P _D @T _A =25°C	Total Power Dissipation ⁴	5	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-ambient ¹	---	41	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	10	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=30\text{V}$, $V_{GS}=0\text{V}$,	-	-	1.0	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0\text{V}$, $V_{GS}=\pm20\text{V}$	-	-	±100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	1.0	1.5	2.5	V
$R_{DS(\text{on})}$ note3	Static Drain-Source on-Resistance	$V_{GS}=10\text{V}$, $I_D=15\text{A}$	-	7.0	9	mΩ
		$V_{GS}=4.5\text{V}$, $I_D=10\text{A}$	-	11	14	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=15\text{V}$, $V_{GS}=0\text{V}$, $f=1.0\text{MHz}$	-	1116	-	pF
C_{oss}	Output Capacitance		-	187	-	pF
C_{rss}	Reverse Transfer Capacitance		-	152	-	pF
Q_g	Total Gate Charge	$V_{DS}=15\text{V}$, $I_D=8\text{A}$, $V_{GS}=10\text{V}$	-	13.3	-	nC
Q_{gs}	Gate-Source Charge		-	3.1	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	5	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=15\text{V}$, $I_D=15\text{A}$, $R_{GEN}=3\Omega$, $V_{GS}=10\text{V}$	-	15	-	ns
t_r	Turn-on Rise Time		-	19	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	35	-	ns
t_f	Turn-off Fall Time		-	21	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	15	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	60	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_S=15\text{A}$	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	$I_F=15\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$	-	14	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	4.1	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: $T_J=25^\circ\text{C}$, $V_{GS}=15\text{V}$, $R_G=25\Omega$, $L=0.5\text{mH}$, $I_{AS}=12.6\text{A}$

3. Pulse Test: Pulse Width $\leq300\mu\text{s}$, Duty Cycle $\leq0.5\%$

Typical Performance Characteristics

Figure 1: Output Characteristics

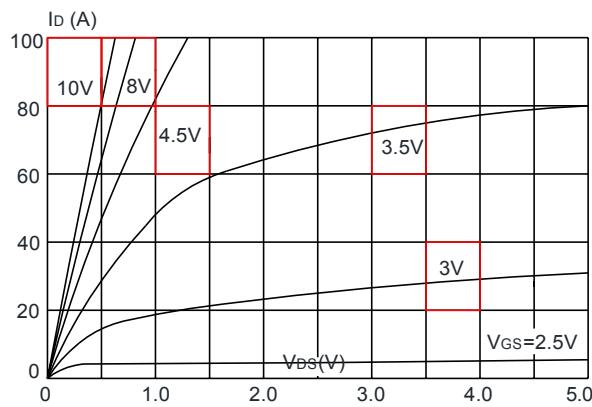


Figure 3: On-resistance vs. Drain Current

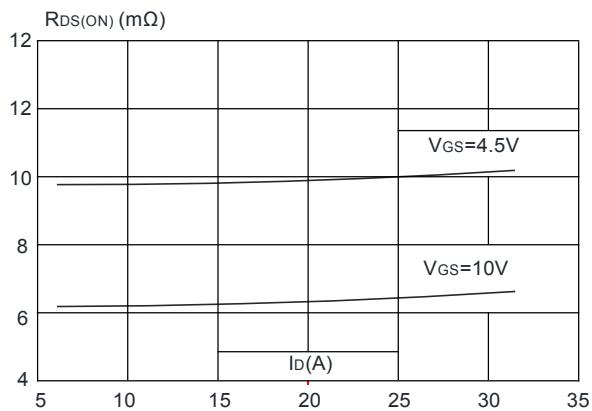


Figure 5: Gate Charge Characteristics

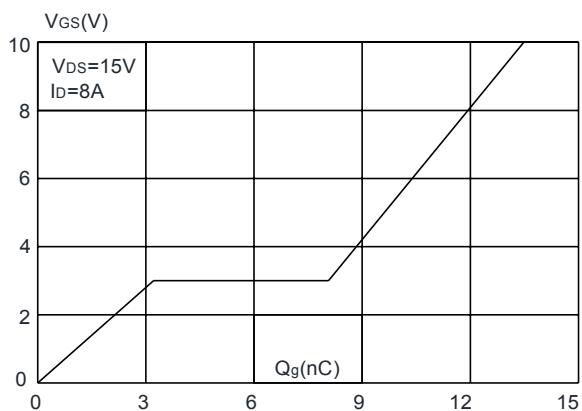


Figure 2: Typical Transfer Characteristics

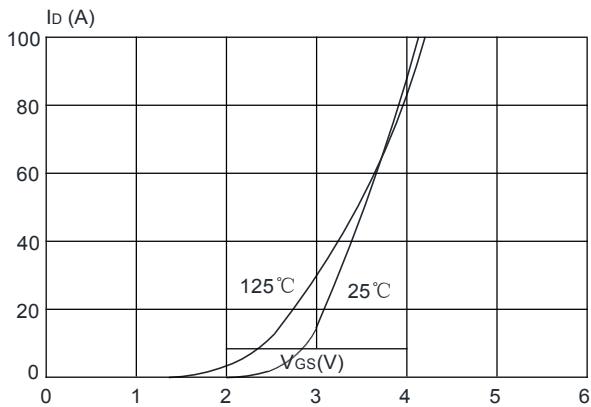


Figure 4: Body Diode Characteristics

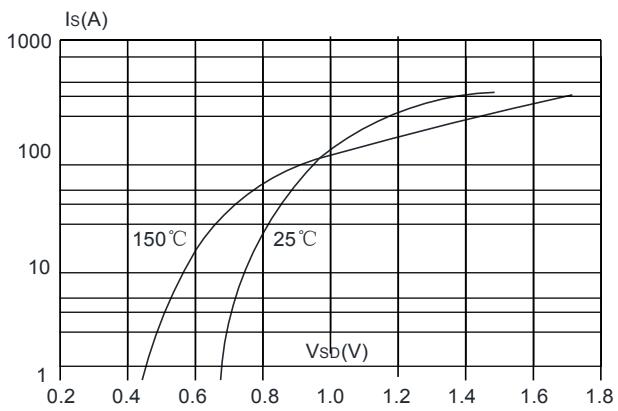


Figure 6: Capacitance Characteristics

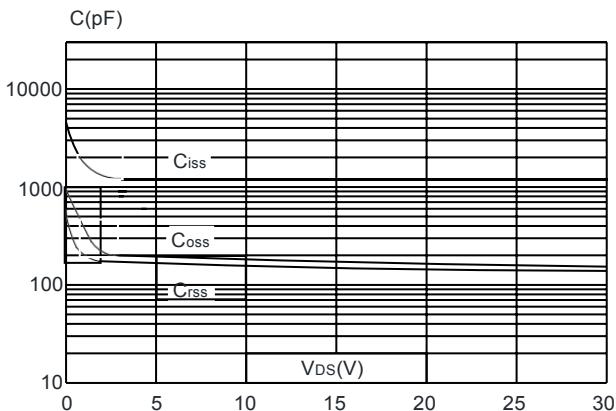


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

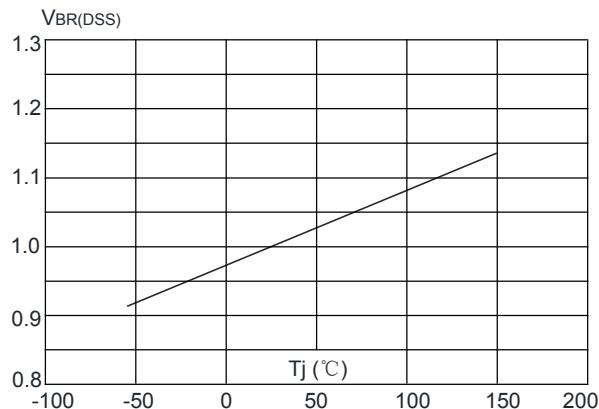


Figure 8: Normalized on Resistance vs. Junction Temperature

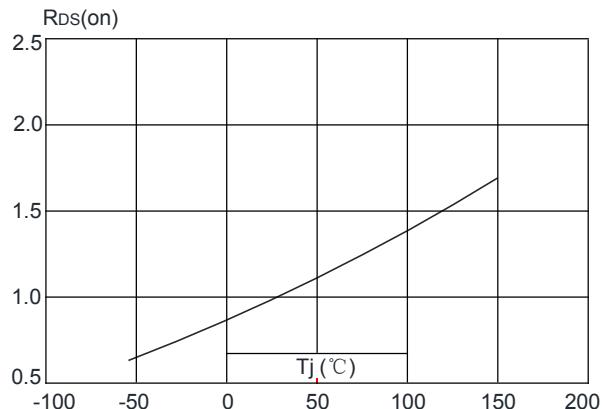


Figure 9: Maximum Safe Operating Area

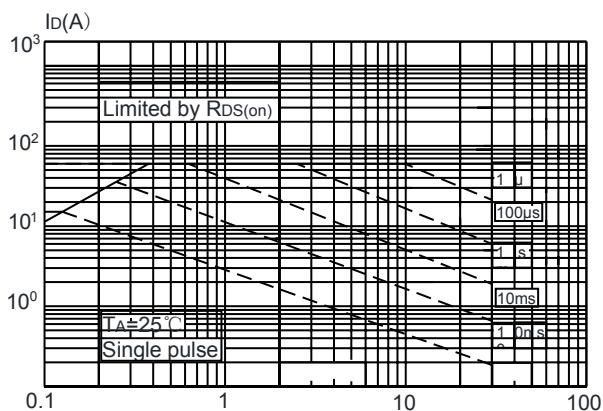


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

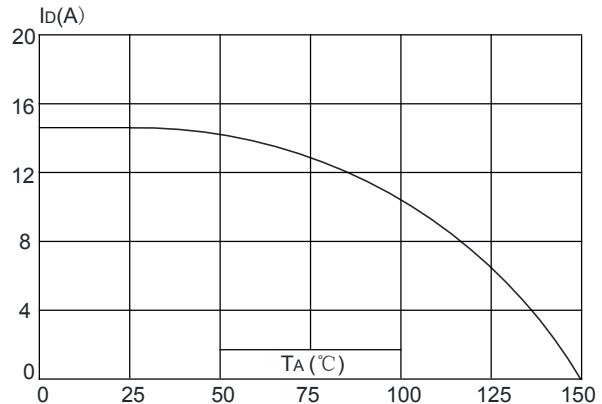
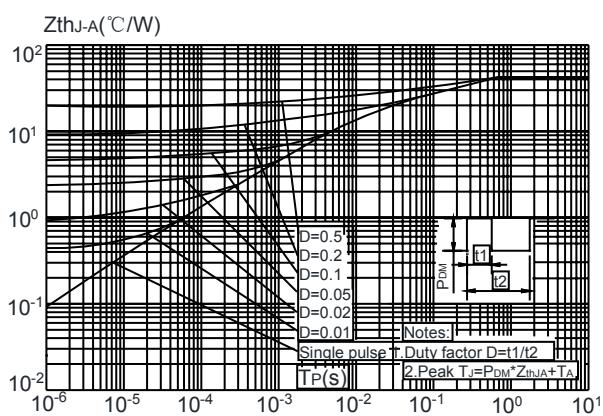
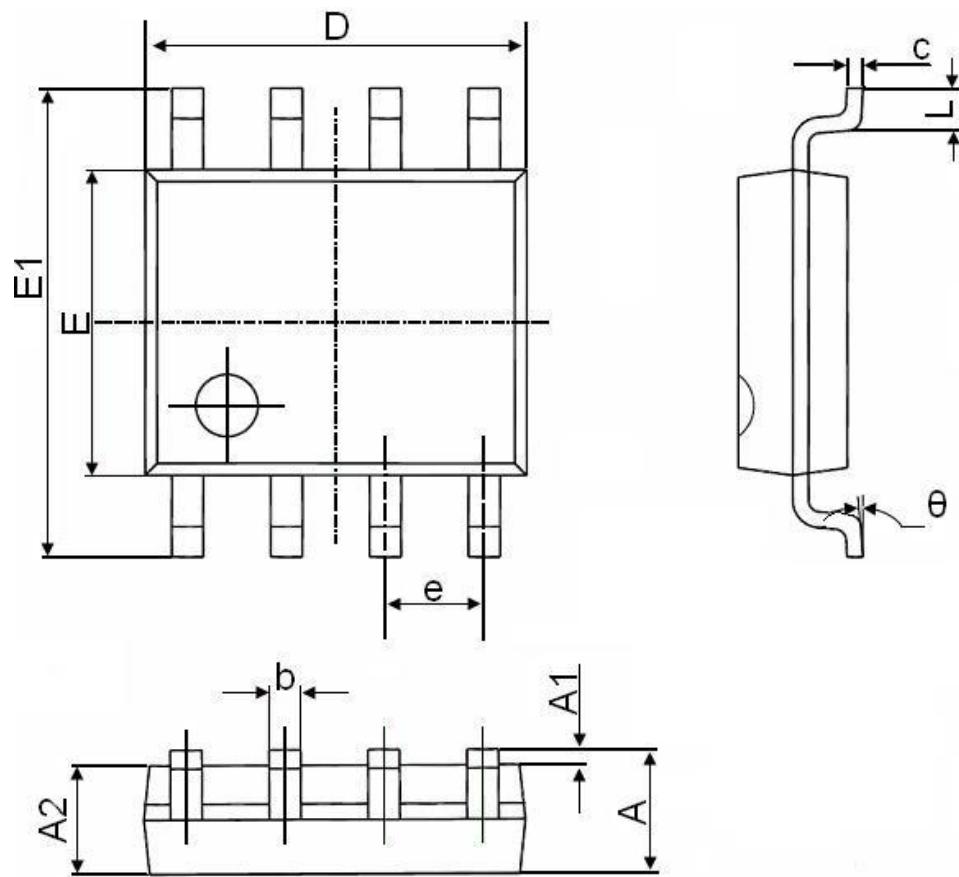


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



SOP-8 Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°